



Thermal Design

Heat Sinks,
Thermoelectrics,
Heat Pipes,
Compact Heat Exchangers,
and Solar Cells

HoSung Lee

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Preface

This book is written as a senior undergraduate or a first-year graduate textbook, covering modern thermal devices such as heat sinks, thermoelectric generators and coolers, heat pipes, compact heat exchangers, and solar cells as design components. These devices are becoming increasingly important and fundamental in thermal design in such diverse areas as microelectronic cooling, green or thermal energy conversion, thermal control and management in space, and so on. However, there is no textbook available that includes these topics, which is the rationale for the writing of this book. This book may be used as a capstone design course after students have finished the fundamental courses in areas such as thermodynamics, fluid mechanics, and heat transfer. The concept of this book is to give the student first an understanding of the physical mechanisms of the devices with detailed derivations, and second, practice in designing the devices with use of mathematical modeling, graphical optimization, and occasionally computational-fluid-dynamic (CFD) simulation. This is done through pertinent design examples developed using a commercial software, MathCAD. In other words, the design concept is embodied through the sample problems. The graphical presentation generally provides designers or students with rich and flexible solutions giving the optimal design.

This book is unique as a textbook of *thermal design* with the present topics and design methodology. It has been developed from the author's lecture notes. Since this book exhibits the fundamental framework of thermal design using modern thermal devices, the applications to the thermal systems associated with these devices are unlimited.

This book is self-contained. For example, an introduction to thermal radiation was added prior to the section of *fin design in space* for the readers who are not familiar with this subject. Many appropriate charts and tables were attached in the appendices so that readers need not look at other reference books. Detailed tutorials appropriate for use in CFD and MathCAD homework problems are also included in the appendices to help students.

Particular effort was made to create figures representing key concepts of the subject matter, keeping in mind that "one good figure is better than a thousand words." Needless to say, figures are important learning tools, focus attention and stimulate curiosity and interest.

In the past decade, a good deal of attention has been given to critically assessing traditional pedagogy and to exploring means by which students' learning may be enhanced. With respect to the development of educational tools and curricula, this assessment has stimulated serious consideration of *learning objectives* and the means of determining the extent to which prescribed objectives are being met. This textbook has three learning objectives:

1. The students should delineate physical mechanisms and transport phenomena for any process or system particularly associated with thermal devices such

- as heat sinks, thermoelectric generators and coolers, heat pipes, compact heat exchangers, and solar cells.
2. The students should be able to develop mathematical models and graphical optimization for any process or system associated with the thermal devices or systems.
 3. The students should be able to professionally design the thermal devices or systems using design tools.

As mentioned before, this book is self-contained. An attempt was made to include necessary background in thermodynamics, fluid mechanics, and heat transfer. Chapter 1 focuses on material needed in later chapters. Students can use this chapter as reference or review. The first and second laws of thermodynamics, internal and external convection flow, and heat transfer mechanisms were presented with essential formulas and empirical correlations.

Chapter 2 is devoted to *heat sinks*, which are the most common thermal devices for use in the electronics industry. They are used to improve the thermal control of electronic components, assemblies, and modulus by enhancing their exterior surface area through the use of fins. The governing formulas on heat dissipation and efficiency for single and multiple fins are derived and incorporated into the modeling and optimization of fin design. Particular effort was given to creating appropriate examples to reflect the design concept, which involves mathematical modeling and graphical optimization. Also in the chapter, fin design with thermal radiation (in space) was explored with two design examples.

Chapter 3 provides the fundamentals of the design of *thermoelectric generators* and *coolers*. The field of thermoelectrics has grown dramatically in recent years, but in spite of this resurgence of interest, there are very few books available. This may be the first book to deal with the design of thermoelectrics and heat pipes, providing the physical principles and fundamental formulas, which lead to mathematical modeling and graphical optimization. This chapter may prompt students to look for the waste energy recovery from the exhaust gases in automotive vehicles and power systems for spacecrafts using radioisotope thermoelectric generators (RTG). A design example at the end of the chapter was conceptualized and developed from a commercial product, which consists of two heat sinks, two fans and a thermoelectric cooler (TEC) module as a thermal system.

Chapter 4 is devoted to the design of *heat pipes*, which have been recently employed in numerous applications ranging from temperature control of the permafrost layer under the Alaska pipeline to the thermal control of optical surfaces in spacecraft. Today every laptop computer has a heat-pipe related cooling system. This book gives a clear understanding of the fundamentals of heat pipes, including the formulas, which allow modeling and optimization in design. This chapter deals with various heat pipes such as variable conductance heat pipe, loop heat pipe, micro heat pipe, and heat pipe in space. The end-of-chapter design example discusses the detailed design aspects: selecting materials and working fluid, sizing the heat pipe, selecting the wick, and performance map.

Chapter 5 discusses the design of *compact heat exchangers* including plate heat exchangers, finned-tube heat exchangers, and plate-fin heat exchangers. In order to discuss these complex exchangers, simpler heat exchangers such as a double-pipe heat exchanger and a shell-and-tube heat exchanger are also introduced. Usually, it takes a semester to cover the entire material of this chapter. However, the complex geometry and time-consuming work are incorporated into the illustrated models. This saves a lot of the students' time. Rather, students can put their efforts either into improving the model or implementing into the system design. Design tools such as MathCAD enable easy and precise minimizing of human errors in calculations.

Chapter 6 is devoted to *solar cell design*. It is often said that solar energy will be the energy in the future. Solar cells need to be developed in order to meet the formidable requirements of high efficiency and low cost. A solar cell is a technology-dependent device, wherein efficiency is a key issue in performance and design. The author believes that solar cells should be dealt with in undergraduate programs, when we consider their importance and huge demand in the future. Unfortunately, a solar cell involves many disciplines: physics, chemistry, materials, electronics, and mechanics (heat transfer). This book was written to provide the fundamentals of solar cells including both the physics and design with a ready-to-use model so that we may achieve our goal in a minimum of time.

Students or teachers should feel free to copy the ready-to-use models to suit their own purposes. This book was designed to provide profound theories and derivation of formulas so that students can easily make modifications or improvements according to their ability. For example, a student who is not strong in physics but is creative can produce a novel design using the ready-to-use models presented in this book.

Except for Chapter 1 ("Introduction"), each chapter is independent from other chapters so that it may be taught separately. Considering the volume of material in each chapter, any combination of three chapters would be appropriate for a semester's material. Chapter 1 may be skipped. For example, a thermal-oriented course would use Chapter 2, "Heat Sinks," Chapter 4, "Heat Pipes," and Chapter 5, "Compact Heat Exchangers." An electronic cooling-oriented course would use Chapter 2, "Heat Sinks," Chapter 3, "Thermoelectrics," and Chapter 4, "Heat Pipes." Intensive design can be sought with Chapter 5, "Compact Heat Exchangers," and Chapter 6, "Solar Cells." This book can be taught for one or two semesters. Note that many problems at the end of each chapter may require at least a week of work by students.

I would like to acknowledge the many suggestions, the inspiration, and the help provided by undergraduate/graduate students in the thermal design classes over the years. I also thank the College of Engineering and Applied Sciences at Western Michigan University for providing me the opportunity to teach the thermal design courses. Particular thanks to the Wiley staff for their support and their editing of the material. I also wish to thank anonymous reviewers for their suggestions and critiques that greatly improved the quality of this book. I am immensely indebted to Professor Emeritus Herman Merte, Jr. for his advice and support in the preparation of this book. My sincere appreciation is extended to Dr. Stanley L. Rajnak for his suggestions and his review in preparation of the manuscript. He reviewed the entire manuscript with his invaluable

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Kalamazoo, Michigan

HoSung Lee

Contents

Preface xv

1 Introduction 1

1.1	Introduction	1
1.2	Humans and Energy	1
1.3	Thermodynamics	2
1.3.1	Energy, Heat, and Work	2
1.3.2	The First Law of Thermodynamics	2
1.3.3	Heat Engines, Refrigerators, and Heat Pumps	5
1.3.4	The Second Law of Thermodynamics	7
1.3.5	Carnot Cycle	7
1.4	Heat Transfer	11
1.4.1	Introduction	11
1.4.2	Conduction	12
1.4.3	Convection	15
1.4.3.1	Parallel Flow on an Isothermal Plate	15
1.4.3.2	A Cylinder in Cross Flow	18
1.4.3.3	Flow in Ducts	18
1.4.3.4	Free Convection	22
1.4.4	Radiation	25
1.4.4.1	Thermal Radiation	25
1.4.4.2	View Factor	29
1.4.4.3	Radiation Exchange between Diffuse-Gray Surfaces	31
References		32

2 Heat Sinks 34

2.1	Longitudinal Fin of Rectangular Profile	34
2.2	Heat Transfer from Fin	36
2.3	Fin Effectiveness	37
2.4	Fin Efficiency	38
2.5	Corrected Profile Length	38
2.6	Optimizations	39
2.6.1	Constant Profile Area A_p	39
2.6.2	Constant Heat Transfer from a Fin	41
2.6.3	Constant Fin Volume or Mass	42
2.7	Multiple Fin Array I	45
2.7.1	Free (Natural) Convection Cooling	45
2.7.1.1	Small Spacing Channel	45

	2.7.1.2	Large Spacing Channel	48
	2.7.1.3	Optimum Fin Spacing	49
	2.7.2	Forced Convection Cooling	49
	2.7.2.1	Small Spacing Channel	49
	2.7.2.2	Large Spacing Channel	51
2.8		Multiple Fin Array II	53
	2.8.1	Natural (Free) Convection Cooling	55
2.9		Thermal Resistance and Overall Surface Efficiency	56
2.10		Fin Design with Thermal Radiation	80
	2.10.1	Single Longitudinal Fin with Radiation	81
		References	94
		Problems	94

3 Thermoelectrics 100

3.1		Introduction	100
3.2		Thermoelectric Effect	102
	3.2.1	Seebeck Effect	102
	3.2.2	Peltier Effect	103
	3.2.3	Thomson Effect	103
	3.2.4	Thomson (or Kelvin) Relationships	103
3.3		Thermoelement Couple (Thermocouple)	104
3.4		The Figure of Merit	104
3.5		Similar and Dissimilar Materials	105
	3.5.1	Similar Materials	105
	3.5.2	Dissimilar Materials	106
3.6		Thermoelectric Generator (TEG)	107
	3.6.1	Similar and Dissimilar Materials	107
		3.6.1.1 Similar Materials	107
		3.6.1.2 Dissimilar Materials	108
	3.6.2	Conversion Efficiency and Current	109
	3.6.3	Maximum Conversion Efficiency	109
	3.6.4	Maximum Power Efficiency	111
	3.6.5	Maximum Performance Parameters	112
	3.6.6	Multicouple Modules	115
3.7		Thermoelectric Coolers (TEC)	126
	3.7.1	Similar and Dissimilar Materials	127
		3.7.1.1 Similar Materials	127
		3.7.1.2 Dissimilar Materials	128
	3.7.2	The Coefficient of Performance	128
	3.7.3	Optimum Current for the Maximum Cooling Rate	129
	3.7.4	Maximum Performance Parameters	129
	3.7.5	Optimum Current for the Maximum <i>COP</i>	130
	3.7.6	Generalized Charts	131

3.7.7	Optimum Geometry for the Maximum Cooling in Similar Materials	132
3.7.8	Thermoelectric Modules	133
3.7.9	Commercial TEC	135
3.7.10	Multistage Modules	135
	3.7.10.1 Commercial Multistage Peltier Modules	137
3.7.11	Design Options	137
3.8	Applications	142
	3.8.1 Thermoelectric Generators	142
	3.8.2 Thermoelectric Coolers	143
3.9	Design Example	143
	3.9.1 Design Concept	144
	3.9.2 Design of Internal and External Heat Sinks	145
	3.9.3 Design of Thermoelectric Cooler (TEC)	149
	3.9.4 Finding the Exact Solution for T_c and T_h	150
	3.9.5 Performance Curves for Thermoelectric Air Cooler	152
3.10	Thermoelectric Module Design	153
	3.10.1 Thermal and Electrical Contact Resistances for TEG	153
	3.10.2 Thermal and Electrical Contact Resistances for TEC	158
3.11	Design Example of TEC Module	166
	3.11.1 Design Concept	166
	3.11.2 Summary of Design of a TEC Module	173
	References	174
	Problems	175

4 Heat Pipes 180

4.1	Operation of Heat Pipe	180
4.2	Surface Tension	181
4.3	Heat Transfer Limitations	183
	4.3.1 Capillary Limitation	184
	4.3.1.1 Maximum Capillary Pressure Difference	185
	4.3.1.2 Vapor Pressure Drop	187
	4.3.1.3 Liquid Pressure Drop	189
	4.3.1.4 Normal Hydrostatic Pressure Drop	189
	4.3.1.5 Axial Hydrostatic Pressure Drop	191
	4.3.2 Approximation for Capillary Pressure Difference	191
	4.3.3 Sonic Limitation	192
	4.3.4 Entrainment Limitation	192
	4.3.5 Boiling Limitation	193
	4.3.6 Viscous Limitation	193
4.4	Heat Pipe Thermal Resistance	197
	4.4.1 Contact Resistance	200
4.5	Variable Conductance Heat Pipes (VCHP)	202
	4.5.1 Gas-Loaded Heat Pipes	203

4.5.2	Clayepyron-Clausius Equation	205
4.5.3	Applications	206
4.6	Loop Heat Pipes	208
4.7	Micro Heat Pipes	210
4.7.1	Steady-State Models	211
4.7.1.1	Conventional Model	211
4.7.1.2	Cotter's Model	212
4.8	Working Fluid	217
4.8.1	Figure of Merit	217
4.8.2	Compatibility	219
4.9	Wick Structures	219
4.10	Design Example	221
4.10.1	Selection of Material and Working Fluid	221
4.10.2	Working Fluid Properties	221
4.10.3	Estimation of Vapor Space Radius	223
4.10.4	Estimation of Operating Limits	223
4.10.4.1	Capillary Limits	223
4.10.4.2	Sonic Limits	223
4.10.4.3	Entrainment Limits	224
4.10.4.4	Boiling Limits	225
4.10.5	Wall Thickness	226
4.10.6	Wick Selection	227
4.10.7	Maximum Arterial Depth	229
4.10.8	Design of Arterial Wick	230
4.10.9	Capillary Limitation	230
4.10.9.1	Liquid Pressure Drop in the Arteries	231
4.10.9.2	Liquid Pressure Drop in the Circumferential Wick	232
4.10.9.3	Vapor Pressure Drop in the Vapor Space	232
4.10.10	Performance Map	234
4.10.11	Check the Temperature Drop	235
	References	236
	Problems	237

5 Compact Heat Exchangers 240

5.1	Introduction	240
5.2	Fundamentals of Heat Exchangers	243
5.2.1	Counterflow and Parallel Flows	243
5.2.2	Overall Heat Transfer Coefficient	245
5.2.3	Log Mean Temperature Difference (LMTD)	247
5.2.4	Flow Properties	249
5.2.5	Nusselt Numbers	250

5.2.6	Effectiveness–NTU (ϵ -NTU) Method	250
5.2.6.1	Parallel Flow	252
5.2.6.2	Counterflow	253
5.2.6.3	Crossflow	253
5.2.7	Heat Exchanger Pressure Drop	257
5.2.8	Fouling Resistances (Fouling Factors)	261
5.2.9	Overall Surface (Fin) Efficiency	262
5.2.10	Reasonable Velocities of Various Fluids in Pipe Flow	264
5.3	Double-Pipe Heat Exchangers	265
5.4	Shell-and-Tube Heat Exchangers	272
5.4.1	Baffles	273
5.4.2	Multiple Passes	273
5.4.3	Dimensions of Shell-and-Tube Heat Exchanger	274
5.4.4	Shell-side Tube Layout	274
5.5	Plate Heat Exchangers (PHE)	285
5.5.1	Flow Pass Arrangements	285
5.5.2	Geometric Properties	286
5.5.3	Friction Factor	290
5.5.4	Nusselt Number	290
5.5.5	Pressure Drops	290
5.6	Pressure Drops in Compact Heat Exchangers	303
5.6.1	Fundamentals of Core Pressure Drop	304
5.6.2	Core Entrance and Exit Pressure Drops	306
5.6.3	Contraction and Expansion Loss Coefficients	307
5.6.3.1	Circular-Tube Core	308
5.6.3.2	Square-Tube Core	309
5.6.3.3	Flat-Tube Core	310
5.6.3.4	Triangular-Tube Core	311
5.7	Finned-Tube Heat Exchangers	312
5.7.1	Geometrical Characteristics	313
5.7.2	Flow Properties	315
5.7.3	Thermal Properties	315
5.7.4	Correlations for Circular Finned-Tube Geometry	316
5.7.5	Pressure Drop	317
5.7.6	Correlations for Louvered Plate-Fin Flat-Tube Geometry	318
5.8	Plate-Fin Heat Exchangers	332
5.8.1	Geometric Characteristics	333
5.8.2	Correlations for Offset Strip Fin (OSF) Geometry	335
5.9	Louver-Fin-Type Flat-Tube Plate-Fin Heat Exchangers	352
5.9.1	Geometric Characteristics	352
5.9.2	Correlations for Louver Fin Geometry	355
	References	372
	Problems	373

6 Solar Cells 382

6.1	Introduction	382
6.1.1	Operation of Solar Cells	384
6.1.2	Solar Cells and Technology	386
6.1.3	Solar Irradiance	387
6.1.4	Air Mass	388
6.1.5	Nature of Light	389
6.2	Quantum Mechanics	390
6.2.1	Atomic Structure	392
6.2.2	Bohr's Model	393
6.2.3	Line Spectra	394
6.2.4	De Broglie Wave	396
6.2.5	Heisenberg Uncertainty Principle	397
6.2.6	Schrödinger Equation	397
6.2.7	A Particle in a 1-D Box	398
6.2.8	Quantum Numbers	401
6.2.9	Electron Configurations	403
6.2.10	Van der Waals Forces	405
6.2.11	Covalent Bonding	405
6.2.12	Energy Band	406
6.2.13	Pseudo-Potential Well	407
6.3	Density of States	408
6.3.1	Number of States	408
6.3.2	Effective Mass	409
6.4	Equilibrium Intrinsic Carrier Concentration	409
6.4.1	Fermi Function	410
6.4.2	Nondegenerate Semiconductor	411
6.4.3	Equilibrium Electron and Hole Concentrations	411
6.4.4	Intrinsic Semiconductors	413
6.4.5	Intrinsic Carrier Concentration, n_i	414
6.4.6	Intrinsic Fermi Energy	415
6.4.7	Alternative Expression for n_0 and p_0	416
6.5	Extrinsic Semiconductors in Thermal Equilibrium	416
6.5.1	Doping, Donors, and Acceptors	417
6.5.2	Extrinsic Carrier Concentration in Equilibrium	418
6.5.3	Built-in Voltage	420
6.5.4	Principle of Detailed Balance	421
6.5.5	Majority and Minority Carriers in Equilibrium	421
6.6	Generation and Recombination	422
6.6.1	Direct and Indirect Band Gap Semiconductors	422
6.6.2	Absorption Coefficient	424
6.6.3	Photogeneration	424

6.7	Recombination	425	
6.7.1	Recombination Mechanisms	425	
6.7.2	Band Energy Diagram under Nonequilibrium Conditions		427
6.7.2.1	Back Surface Field (BSF)	427	
6.7.3	Low-Level Injection	429	
6.7.3.1	Low-Level Injection	429	
6.7.4	Band-to-Band Recombination	430	
6.7.5	Trap-Assisted (SRH) Recombination	431	
6.7.6	Simplified Expression of the SRH Recombination Rate		433
6.7.7	Auger Recombination	434	
6.7.8	Total Recombination Rate	435	
6.8	Carrier Transport	436	
6.8.1	Drift	436	
6.8.2	Carrier Mobility	436	
6.8.3	Diffusion	437	
6.8.4	Total Current Densities	438	
6.8.5	Einstein Relationship	439	
6.8.6	Semiconductor Equations	440	
6.8.7	Minority-Carrier Diffusion Equations	440	
6.8.8	P–n Junction	441	
6.8.9	Calculation of Depletion Width	444	
6.8.10	Energy Band Diagram with a Reference Point		445
6.8.11	Quasi-Fermi Energy Levels	446	
6.9	Minority Carrier Transport	447	
6.9.1	Boundary Conditions	448	
6.9.2	Minority Carrier Lifetimes	449	
6.9.3	Minority Carrier Diffusion Lengths	450	
6.9.4	Minority Carrier Diffusion Equation for Holes	450	
6.9.5	Minority Carrier Diffusion Equation for Electrons	454	
6.10	Characteristics of Solar Cells	457	
6.10.1	Current Density	457	
6.10.2	Current-Voltage Characteristics	463	
6.10.3	Figures of Merit	466	
6.10.4	Effect of Minority Electron Lifetime on Efficiency	468	
6.10.5	Effect of Minority Hole Lifetime on Efficiency	470	
6.10.6	Effect of Back Surface Recombination Velocity on Efficiency		470
6.10.7	Effect of Base Width on Efficiency	471	
6.10.8	Effect of Emitter Width W_N on Efficiency	472	
6.10.9	Effect of Acceptor Concentration on Efficiency	474	
6.10.10	Effect of Donor Concentration on Efficiency	475	
6.10.11	Band Gap Energy with Temperature	476	
6.10.12	Effect of Temperature on Efficiency	477	

6.11	Additional Topics	478
6.11.1	Parasitic Resistance Effects (Ohmic Losses)	478
6.11.2	Quantum Efficiency	481
6.11.3	Ideal Solar Cell Efficiency	483
6.12	Modeling	488
6.12.1	Modeling for a Silicon Solar Cell	488
6.12.2	Comparison of the Solar Cell Model with a Commercial Product	503
6.13	Design of a Solar Cell	506
6.13.1	Solar Cell Geometry with Surface Recombination Velocities	506
6.13.2	Donor and Acceptor Concentrations	507
6.13.3	Minority Carrier Diffusion Lifetimes	507
6.13.4	Grid Spacing	508
6.13.5	Anti-Reflection, Light Trapping and Passivation	512
	References	512
	Problems	513

Appendix A Thermophysical Properties 518

Appendix B Thermoelectrics 561

B.1	Thermoelectric Effects	561
	Seebeck Effect	561
	Peltier Effect	562
	Thomson Effect	562
B.2	Thomson (or Kelvin) Relationships	562
B.3	Heat Balance Equation	566
B.4	Figure of Merit and Optimum Geometry	568
	References	573

Appendix C Pipe Dimensions 574

Appendix D Curve Fitting of Working Fluids 576

	Curve Fit for Working Fluids Chosen	576
D.1	Curve Fitting for Working Fluid Properties Chosen	576
D.1.1	MathCad Format	576

Appendix E Tutorial I for 2-D 580

	Problem Description for Tutorial I	580
E.1	Tutorial I: Using Gambit and Fluent for Thermal Behavior of an Electrical Wire	581
E.1.1	Creating Geometry in Gambit	581
E.2	Calculations for Heat Generation	588

Appendix F Tutorial II for 3-D 590

Problem Description for Tutorial II	590
F.1 Tutorial II Double-Pipe Heat Exchanger: Using SolidWorks, Gambit, and Fluent	591
F.1.1 Double-Pipe Heat Exchanger	591
F.1.2 Construct Model in SolidWorks	591
F.1.3 Meshing the Double Pipe Heat Exchanger in Gambit	595
F.1.4 Analysis of Heat Exchanger in Fluent	600

Appendix G Computational Work of Heat Pipe 605

G.1 A Heat Pipe and Heat Sink	605
-------------------------------	-----

Appendix H Computational Work of a Heat Sink 607

H.1 Electronic Package Cooling	607
--------------------------------	-----

Appendix I Tutorial for MathCAD 608

I.1 Tutorial Problem for MathCAD	608
----------------------------------	-----

Index 613
